



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20261013004.1	PCN Issued	October 15, 2026
Qualification of RFAB as an additional Wafer Fab site, Assembly Site options, BOM, and Datasheet updates for select devices		Sample request deadline:	December 14, 2026
		Estimated 1st ship date:	January 13, 2027
Sample requests received after December 14, 2026 will not be supported.			

Change type(s)
Packing/Shipping/Labeling Wafer Fab Site Wafer Fab Process Wafer Fab Material Assembly Site Assembly Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site option using LBC9 process technology, BOM and datasheet updates for the products listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process Technology	Wafer Diameter	Additional Fab site	Process Technology	Wafer Diameter
FFAB	ASLNONC10	200mm	RFAB	LBC9	300mm

Construction differences are as follows:

Group 1

	Current	New
Bond wire material / diameter	Cu; 0.96mil	Cu; 0.8mil

Group 2

	Current Site	Additional Site
Assembly Site	FMX	MLA
Bond wire material / diameter	Cu; 0.96mil	Cu; 0.8mil

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history shown below. The links to the revised datasheets are available in the table below.

Changes from Revision D (January 2026) to Revision E (September 2026) Page

• Added DYY package.....	1
• Updated Thermal Information.....	5
• Updated Electrical Characteristics.....	5
• Updated Switching Characteristics.....	6

Changes from Revision D (September 2021) to Revision E (September 2026) Page

• Updated Thermal Information.....	5
• Updated Electrical Characteristics.....	5
• Updated Switching Characteristics.....	6

Changes from Revision E (January 2011) to Revision F (September 2026) Page

• Removed ordering information.....	1
• Added package diagram.....	1
• Added Pin Configuration and Functions.....	3
• Updated Thermal Information.....	5
• Updated Electrical Characteristics.....	5
• Updated Switching Characteristics.....	6

Changes from Revision D (November 2003) to Revision E (September 2026) Page

• Updated the number formatting for tables, figures, and cross-references throughout the document.....	1
• Removed Ordering Information table.....	1
• Added ESD Ratings table.....	6
• Added the <i>Thermal Information</i> table and moved $R_{\theta JA}$ values to the table.....	7
• Updated the maximum per control input parameter in <i>Electrical Characteristics</i>	7
• Updated the maximum V_{CC} rating for t_{en} and t_{dis} in the <i>Switching Characteristics</i> table.....	8

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74CB3Q3125	SCDS143D	SCDS143E	http://www.ti.com/product/SN74CB3Q3125
SN74CB3Q3305	SCDS141D	SCDS141E	http://www.ti.com/product/SN74CB3Q3305
SN74CB3Q3306A	SCDS113E	SCDS113F	http://www.ti.com/product/SN74CB3Q3306A
SN74CB3Q3384A	SCDS114D	SCDS114E	http://www.ti.com/product/SN74CB3Q3384A

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:

- Request the Supporting Data Packet for more details on the changes.
- There are changes in the electrical tables.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:**Fab Site Information**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	RFB	USA	Richardson

Die Rev:**Current****New**

Die Rev [2P]	Die Rev [2P]
G, B	-

Assembly Site Information

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
FMX	MEX	MEX	Aguascalientes
MLA	MLA	MYS	KUALA LUMPUR

Sample product shipping label (not actual product label):

**Products Affected: Fab and Group 1**

SN74CB3Q3305PWR	SN74CB3Q3305PW RG4	SN74CB3Q3305PW RE4	SN74CB3Q3384APWR
SN74CB3Q3306APWR	SN74CB3Q3306APWR G4	SN74CB3Q3125PWR	SN74CB3Q3384ADBQR

Products Affected: Fab and Group 2

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3384ADBQR	QBS Reference: TLV62568DBVR	QBS Reference: 74ACT16374DLR	QBS Reference: TLC6946DBQR	QBS Reference: GD75232DBR	QBS Reference: SN74CB3Q3384APWR	QBS Reference: SN74CB3T3245DBQR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	1/77/0	-	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/231/0	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	1/3/0	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	-	-	-	1/30/0	1/30/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3384ADBQR is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3384APWR	QBS Reference: TLV62568DBVR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: LM324BJPWR	QBS Reference: SN74HCS08QPWRQ1	QBS Reference: SN74AC165PWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/231/0	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	3/45/0	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3384APWR	QBS Reference: TLV62568DBVR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: LM324BIPWR	QBS Reference: SN74HCS08QPWRQ1	QBS Reference: SN74AC165PWRQ1
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	3/30/0	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3384APWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2410-058

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3125PWR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74HCS74QPWRQ1	QBS Package Reference: SN74AC165PWRQ1	QBS Product Reference: SN74CB3Q3125DBQR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	1/45/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3125PWR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74HCS74QPWRQ1	QBS Package Reference: SN74AC165PWRQ1	QBS Product Reference: SN74CB3Q3125DBQR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	1/30/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3125PWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2410-057

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3305PWR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74HCS74QPWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3305PWR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74HCS74QPWRQ1
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3305PWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2410-059

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3306APWR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74HCS74QPWRQ1	QBS Package Reference: SN74HCS08QPWRQ1	QBS Package Reference: SN74AC165PWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	1/45/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3306APWR	QBS Process Reference: TLV62568DBVR	QBS Package Reference: SN74HCS74QPWRQ1	QBS Package Reference: SN74HCS08QPWRQ1	QBS Package Reference: SN74AC165PWRQ1
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	3/45/0	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3306APWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CB3Q3125DBQR	QBS Reference: TLV62568DBVR	QBS Reference: 74ACT16374DLR	QBS Reference: SN74LV244ADBR	QBS Reference: GD75232DBR	QBS Reference: SN74CB3Q3125PWR	QBS Reference: SN74CB3T3245DBQR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	-	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	-	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77	1/77/0	-	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3125DBQR is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2511-017

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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